IN THE CLAIMS

Claim 1 (currently amended). A method of producing a pressure-sensitive adhesive article having at least one layer of an electrically conductive pressure-sensitive adhesive, characterized in that wherein a layer of the an electrically conductive pressure-sensitive adhesive that is anisotropic at least in respect of one property is produced in a coating process by stretching, drawing or compressing, said layer possessing in at least one direction along the plane of the layer a shrinkback of at least 3% in respect of the longitudinal extent of the layer, measured on the free pressure-sensitive adhesive film.

Claim 2 (currently amended). The method of claim 1, characterized in that wherein the coating process is a hotmelt roll coating process, a melt diecoating process or an extrusion coating process.

Claim 3 (currently amended). The method of claim 1, characterized in that the wherein said coating process is a conventional coating process with comprises subsequent stretching or drawing on a stretchable carrier.

Claim 4 (currently amended). The method of any one of claims 1 to 3, characterized in that claim 1, wherein the electrically conductive pressure-sensitive adhesive is coated onto one or both sides of a sheetlike or tapelike carrier.

Claim 5 (currently amended). The method of claim 4, characterized in that wherein the carrier is a transfer tape, a release liner or an electrically conducting carrier material.

Claim 6 (currently amended). The method of any one of claims 1 to 5, characterized in that <u>claim 1</u>, wherein the pressure-sensitive adhesive used is based on polyacrylate and/or polymethacrylate.

Claim 7 (currently amended). The method of claim 6, characterized in that wherein the pressure-sensitive adhesive is based to an extent of at least 50% by weight on at least one acrylic monomer selected from the group consisting of the compounds of the following general formula:

$$O$$
 R_2

where R_1 = H or CH_3 and the radical R_2 = H or CH_3 or is **chosen selected** from the group **consisting** of the branched or unbranched, saturated alkyl groups having 2 – 30 carbon atoms and the average molecular weight M_W of the pressure-sensitive adhesive is at least 200 000 g/mol.

Claim 8 (currently amended). The method of any one of claims 1 to 6, characterized in that claim 1, wherein the pressure-sensitive adhesive comprises crosslinkers, especially difunctional or polyfunctional acrylates and/or methacrylates, difunctional or polyfunctional isocyanates or difunctional or polyfunctional epoxides, have been added to the pressure-sensitive adhesive.

Claim 9 (currently amended). The method of claim 8, characterized in that wherein the pressure-sensitive adhesive is crosslinked, preferably photochemically, immediately after or during hotmelt coating.

Claim 10 (currently amended). The method of any one of claims 1 to 9, characterized in that claim 1, wherein the pressure-sensitive adhesive comprises electrically conductive materials, especially metal particles, metal powders, metal beads, metal fibers, the metals being in particular nickel, gold, silver and copper or the following nickel-coated particles: copper particles, nickel particles, polymer beads, polymer particles or glass microbeads or hollow glass microbeads, have been admixed to the pressure-sensitive adhesive.

Claim 11 (currently amended). The method of claim 10, characterized in that wherein the electrically conductive materials are admixed in a fraction of present in an amount of up to 200% by weight, preferably between 5% and 50% by weight, more preferably between 10% and 40% by weight, based on the weight of the pressure-sensitive adhesive without the electrically conductive materials.

Claim 12 (currently amended). The method of any one of claims 1 to 11, characterized in that claim 1, wherein the electrical conductivity of the pressure-sensitive adhesive is between 1 and 500 S/cm.

Claim 13 (currently amended). The method of any one of claims 1 to 12, characterized in that claim 1, wherein the electrical conductivity is anisotropic and is lower along a plane lying in the pressure-sensitive adhesive layer than transverse to the plane of the layer, it being at least 2 S/cm in a direction transverse to the plane of the layer.

Claim 14 (currently amended). The method of any one of claims 1 to 13, characterized in that claim 1, wherein the pressure-sensitive adhesive comprises further substances or additives, such as aging inhibitors, light stabilizers, ozone protectants, fatty acids, plasticizers, nucleators, expandants, accelerators and/or fillers.

Claim 15 (currently amended). A pressure-sensitive adhesive article, in particular for bonding two electrical parts, obtainable by a obtained by the method of any one of claims 1 to 14 claim 1.

Claim 16 (original). The pressure-sensitive adhesive article of claim 15 in the form of a die

Claim 17 (new). The method of claim 8, wherein said crosslinkers are selected from the group consisting of diffunctional or polyfunctional acrylates and/or methacrylates, diffunctional or polyfunctional isocyanates and diffunctional or polyfunctional epoxides,

Claim 18 (new). The method of claim 10, wherein said electrically conductive materials are selected from the group consisting of metal particles, metal powders, metal beads, metal fibers, nickel-coated copper particles, nickel-coated nickel particles, nickel-coated polymer beads, nickel-coated polymer particles, nickel-coated glass microbeads and nickel-coated hollow glass microbeads.

Claim 19 (new). The method of claim 11, wherein said amount is between 5% and 50% by weight.

Claim 20 (new). The method of claim 19, wherein said amount is between 10% and 40% by weight.

Claim 21 (new). The method of claim 14, wherein said substances or additives are selected from the group consisting of aging inhibitors, light stabilizers, ozone protectants, fatty acids, plasticizers, nucleators, expandants, accelerators and fillers.